

WHAT IS CLAIMED IS:

1. A method for manufacturing a double-sided flexible printed board, comprising the following steps of:

- (A) forming a polyimide precursor layer on a metal layer;
- (B) forming an upper circuit layer on the polyimide precursor layer by a semi-additive technique; and
- (C) imidating the polyimide precursor layer to form a polyimide insulating layer.

2. The method according to claim 1, wherein step (M) in which the formation of a through hole for ensuring conductivity between the metal layer and the upper circuit layer is performed between step (B) and step (C) or subsequent to step (C).